

SBOS271B - MAY 2003 - REVISED JUNE 2005

# Low-Noise, High-Speed, 16-Bit Accurate, CMOS OPERATIONAL AMPLIFIER

#### **FEATURES**

High Bandwidth: 150MHz16-Bit Settling in 150ns

Low Noise: 3nV/√Hz
Low Distortion: 0.003%

Low Power: 9.5mA (typ) on 5.5V

Shutdown to 5µAUnity-Gain Stable

Excellent Output Swing:
(V+) - 100mV to (V-) + 100mV

• Single Supply: +2.7V to +5.5V

Tiny Packages: MSOP and SOT23

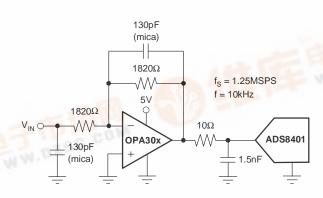
### **APPLICATIONS**

- 16-Bit ADC Input Drivers
- Low-Noise Preamplifiers
- IF/RF Amplifiers
- Active Filtering

#### DESCRIPTION

The OPA300 and OPA301 series high-speed, voltage-feedback, CMOS operational amplifiers are designed for 16-bit resolution systems. The OPA300/OPA301 series are unity-gain stable and feature excellent settling and harmonic distortion specifications. Low power applications benefit from low quiescent current. The OPA300 and OPA2300 feature a digital shutdown (Enable) function to provide additional power savings during idle periods. Optimized for single-supply operation, the OPA300/OPA301 series offer superior output swing and excellent common-mode range.

The OPA300 and OPA301 series op amps have 150MHz of unity-gain bandwidth, low  $3nV/\sqrt{Hz}$  voltage noise, and 0.1% settling within 30ns. Single-supply operation from 2.7V ( $\pm 1.35V$ ) to 5.5V ( $\pm 2.75V$ ) and an available shutdown function that reduces supply current to 5 $\mu$ A are useful for portable low-power applications. The OPA300 and OPA301 are available in SO-8 and SOT-23 packages. The OPA2300 is available in MSOP-10, and the OPA2301 is available in SO-8 and MSOP-8. All versions are specified over the industrial temperature range of  $-40^{\circ}$ C to  $+125^{\circ}$ C.



Typical Application

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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### PACKAGE/ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	PACKAGE MARKING
OPA300	SO-8	D	300A
OPA300	SOT23-6	DBV	A52
OPA301	SO-8	D	301A
OPA301	SOT23-5	DBV	AUP
OPA2300	MSOP-10	DGS	C01
OPA2301	SO-8	D	OPA2301A
OPA2301	MSOP-8	DGK	C02

<sup>(1)</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

#### **ABSOLUTE MAXIMUM RATINGS**

over operating free-air temperature range unless otherwise noted(1)

Power Supply V+	
Signal Input Terminals(2), Voltage 0.5V to (V+)	+ 0.5V
Current	
Open Short-Circuit Current(3) Con	tinuous
Operating Temperature Range55°C to	+125°C
Storage Temperature Range	+150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
ESD Ratings	
Human Body Model (HBM)	4kV
Charged-Device Model (CDM)	500V

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
- (2) Input terminals are diode clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground; one amplifier per package.

#### **ELECTROSTATIC DISCHARGE SENSITIVITY**

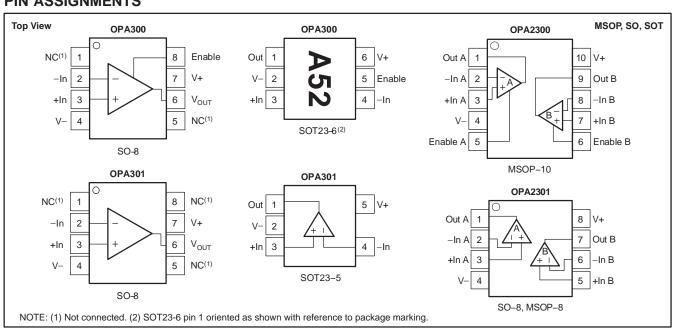


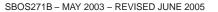
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe

proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### **PIN ASSIGNMENTS**





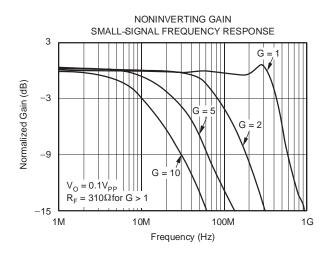


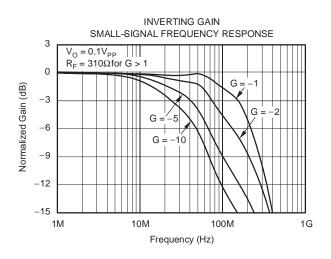
**ELECTRICAL CHARACTERISTICS:**  $V_S = 2.7V$  to 5.5V **Boldface** limits apply over the temperature range,  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$ . All specifications at  $T_A = +25^{\circ}C$ ,  $R_L = 2k\Omega$  connected to  $V_S/2$ ,  $V_{OUT} = V_S/2$ , and  $V_{CM} = V_S/2$ , unless otherwise noted.

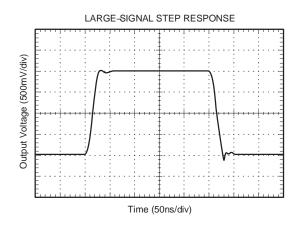
		-	OPA300, OPA301 OPA2300, OPA2301			
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
OFFSET VOLTAGE						
Input Offset Voltage	Vos	V <sub>S</sub> = 5V		1	5	mV
Over Temperature					7	mV
Drift	dV <sub>OS</sub> /dT			2.5		μ <b>۷/</b> °C
vs. Power Supply	PSRR	$V_S = 2.7V \text{ to } 5.5V, V_{CM} < (V+) -0.9V$		50	200	μ <b>V/V</b>
Channel Separation, dc				140		dB
f = 5MHz				100		dB
INPUT VOLTAGE RANGE						
Common-Mode Voltage Range	V <sub>CM</sub>		(V-) - 0.2		(V+) - 0.9	V
Common-Mode Rejection Ratio	CMRR	$(V-) - 0.2V < V_{CM} < (V+) - 0.9V$	66	80		dB
INPUT BIAS CURRENT						
Input Bias Current	ΙΒ			±0.1	±5	pA
Input Offset Current	los			±0.5	±5	pA
INPUT IMPEDANCE						
Differential				10 <sup>13</sup>    3		$\Omega \parallel pF$
Common-Mode				10 <sup>13</sup>    6		Ω    pF
NOISE						
Input Voltage Noise, f = 0.1Hz to 1MHz				40		$\mu V_{PP}$
Input Voltage Noise Density, f > 1MHz	e <sub>n</sub>			3		nV/√Hz
Input Current Noise Density, f < 1kHz	in			1.5		fA/√Hz
Differential Gain Error	"	NTSC, $R_L = 150\Omega$		0.01		%
Differential Phase Error		NTSC, $R_{\rm I} = 150\Omega$		0.1		0
OPEN-LOOP GAIN		· <b>-</b>				
Open-Loop Voltage Gain	AOL	$V_S = 5V$ , $R_I = 2k\Omega$ , $0.1V < V_O < 4.9V$	95	106		dB
Over Temperature	OL	$V_S = 5V$ , $R_L = 2k\Omega$ , $0.1V < V_O < 4.9V$	90			dB
·		$V_S = 5V$ , $R_L = 100\Omega$ , $0.5V < V_O < 4.5V$	95	106	İ	dB
Over Temperature		$V_S = 5V$ , $R_L = 100\Omega$ , $0.5V < V_O < 4.5V$	90			dB
OUTPUT						
Voltage Output Swing from Rail		$R_{I} = 2k\Omega, A_{OI} > 95dB$		75	100	mV
remage carpai camig actions		$R_{I} = 100\Omega$ , $A_{OI} > 95dB$		300	500	mV
Short-Circuit Current	lsc		1	70		mA
Capacitive Load Drive	C <sub>LOAD</sub>		See Tv	pical Charac	teristics	
FREQUENCY RESPONSE	FLOAD			,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		
Gain-Bandwidth Product	GBW			150		MHz
Slew Rate	SR	G = +1		80		V/µs
Settling Time, 0.01%	ts	$V_S = 5V, 2V \text{ Step}, G = +1$		90		ns
0.1%	.5	13 01,21 0.00, 0 11		30		ns
Overload Recovery Time		Gain = −1		30		ns
Total Harmonic Distortion + Noise	THD+N	$V_S = 5V$ , $V_O = 3V_{PP}$ , $G = +1$ , $f = 1kHz$		0.003		%
POWER SUPPLY		3, ·O, · · · · · · · · · · · · · · · ·		2.300	1	,,
Specified Voltage Range	Vs		2.7		5.5	V
Operating Voltage Range	*5			2.7 to 5.5	0.0	V
Quiescent Current (per amplifier)	IQ	I <sub>O</sub> = 0		9.5	12	mA
Over Temperature	٠, ٧	.0 •		0.5	13	mA
SHUTDOWN						
<sup>t</sup> OFF				40		ns
ton				5		μs
V <sub>L</sub> (shutdown)			(V-) - 0.2		(V-) + 0.8	V
V <sub>H</sub> (amplifier is active)			(V-) = 0.2 (V-) + 2.5		(V+) + 0.0 (V+) + 0.2	V
I <sub>OSD</sub> (per amplifier)			( , , , 2.3	3	10	μA
TEMPERATURE RANGE				3		μιτ
Specified Range			-40		+125	°C
Operating Range			-40 -55		+125	°C
Storage Range			-55 -60		+125	°C
Thermal Resistance	Δ.,		-60		T100	°C/W
	$\theta_{JA}$			150		°C/W
SO-8, MSOP-8, MSOP-10 SOT23-5, SOT23-6				150 200		°C/W
30123-3, 30123-0				200	Ļ	C/VV

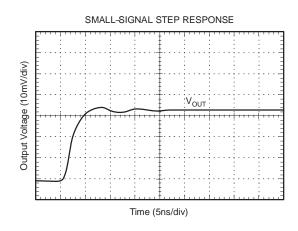


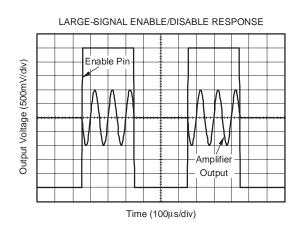
### **TYPICAL CHARACTERISTICS**

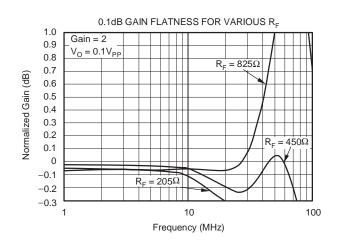






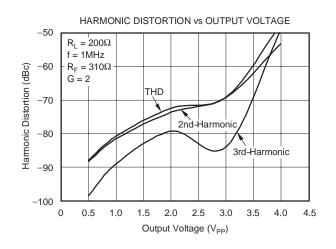


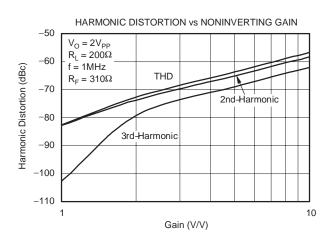


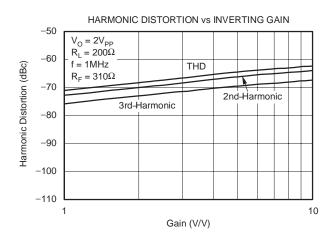


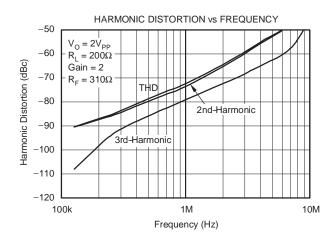


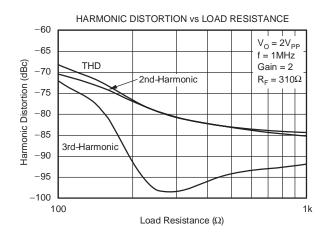
All specifications at  $T_A$  = 25°C,  $V_S$  = 5V, and  $R_L$  = 150 $\Omega$  connected to  $V_S$ /2 unless otherwise noted.

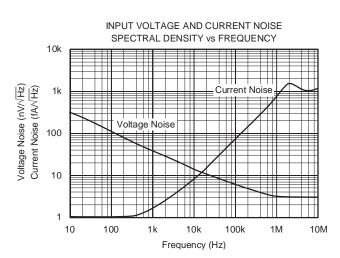




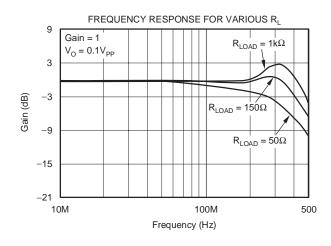


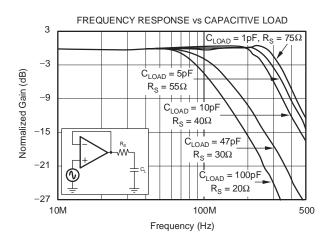


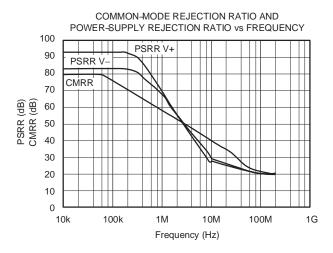


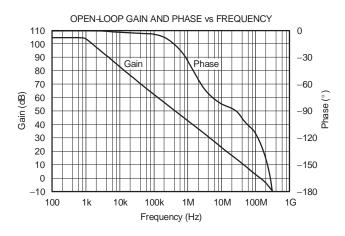


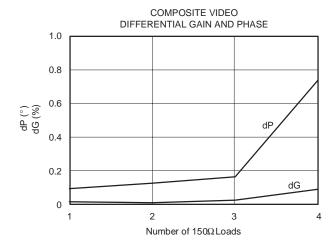


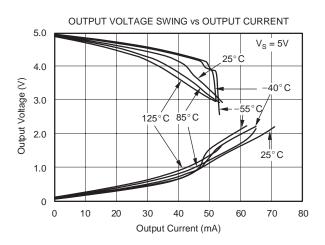




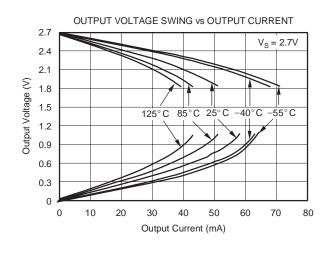


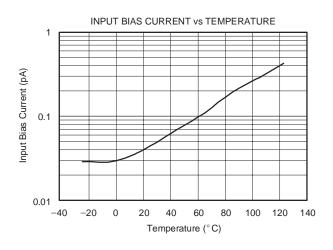


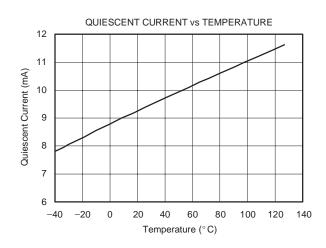


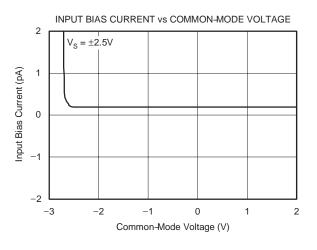


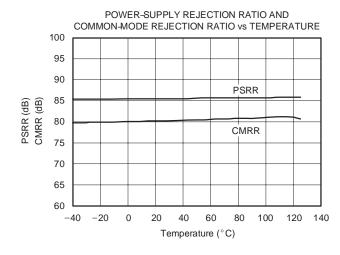


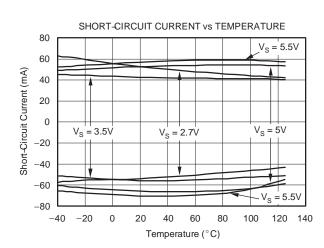




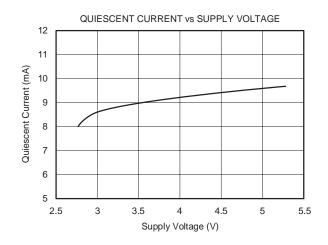


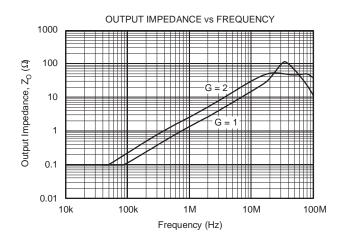


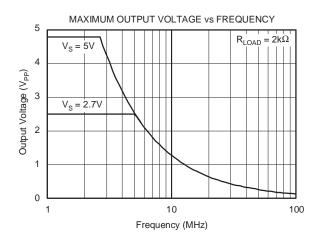


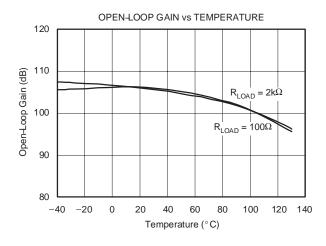


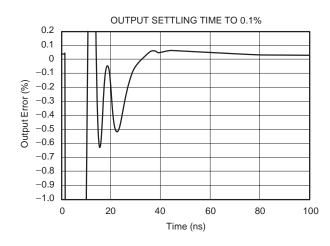


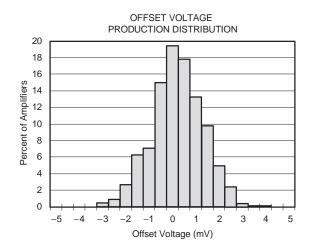




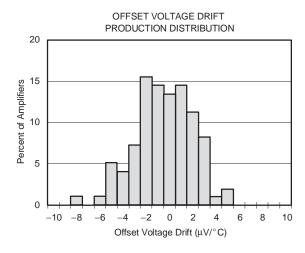














### APPLICATIONS INFORMATION

The OPA300 and OPA301 series of single-supply CMOS op amps are designed to interface with high-speed 16-bit analog-to-digital converters (ADCs). Featuring wide 150MHz bandwidth, fast 150ns settling time to 16 bits, and high open loop gain, this series offers excellent performance in a small SO-8 and tiny SOT23 packages.

### THEORY OF OPERATION

The OPA300 and OPA301 series op amps use a classic two-stage topology, shown in Figure 1. The differential input pair is biased to maximize slew rate without compromising stability or bandwidth. The folded cascode adds the signal from the input pair and presents a differential signal to the class AB output stage. The class AB output stage allows rail- to-rail output swing, with high-impedance loads (>  $2k\Omega$ ), typically 100mV from the supply rails. With  $10\Omega$  loads, a useful output swing can be achieved and still maintain high open-loop gain. See the typical characteristic *Output Voltage Swing vs Output Current*.

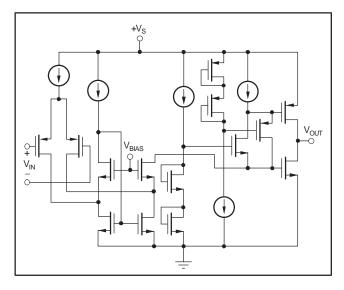


Figure 1. OPA30x Classic Two-Stage Topology

#### **OPERATING VOLTAGE**

OPA300/OPA301 series op amp parameters are fully specified from +2.7V to +5.5V. Supply voltages higher than 5.5V (absolute maximum) can cause permanent damage to the amplifier. Many specifications apply from -40°C to +125°C. Parameters that vary significantly with operating voltages or temperature are shown in the Typical Characteristics.

#### **PCB LAYOUT**

As with most high-speed operational amplifiers, board layout requires special attention to maximize AC and DC performance. Extensive use of ground planes, short lead lengths, and high-quality bypass capacitors will minimize leakage that can compromise signal quality. Guard rings applied with potential as near to the input pins as possible help minimize board leakage.

#### INPUT AND ESD PROTECTION

All OPA300/OPA301 series op amps' pins are staticprotected with internal ESD protection diodes tied to the supplies, as shown in Figure 2. These diodes will provide overdrive protection if the current is externally limited to 10mA, as stated in the Absolute Maximum Ratings. Any input current beyond the Absolute Maximum Ratings, or long-term operation at maximum ratings, will shorten the lifespan of the amplifier.

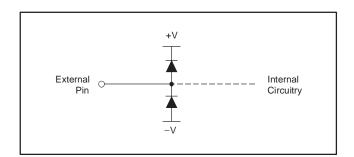


Figure 2. ESD Protection Diodes

#### **ENABLE FUNCTION**

The shutdown function of the OPA300 and OPA2300 is referenced to the negative supply voltage of the operational amplifier. A logic level HIGH enables the op amp. A valid logic HIGH is defined as 2.5V above the negative supply applied to the enable pin. A valid logic LOW is defined as < 0.8V above the negative supply pin. If dual or split power supplies are used, care should be taken to ensure logic input signals are properly referred to the negative supply voltage. If this pin is not connected to a valid high or low voltage, the internal circuitry will pull the node high and enable the part to function.

The logic input is a high-impedance CMOS input. For battery-operated applications, this feature may be used to greatly reduce the average current and extend battery life. The enable time is  $10\mu s$ ; disable time is  $1\mu s$ . When disabled, the output assumes a high-impedance state. This allows the OPA300 to be operated as a gated amplifier, or to have its output multiplexed onto a common analog output bus.



#### DRIVING CAPACITIVE LOADS

When using high-speed operational amplifiers, it is extremely important to consider the effects of capacitive loading on amplifier stability. Capacitive loading will interact with the output impedance of the operational amplifier, and depending on the capacitor value, may significantly decrease the gain bandwidth, as well as introduce peaking. To reduce the effects of capacitive loading and allow for additional capacitive load drive, place a series resistor between the output and the load. This will reduce available bandwidth, but permit stable operation with capacitive loading. Figure 3 illustrates the recommended relationship between the resistor and capacitor values.

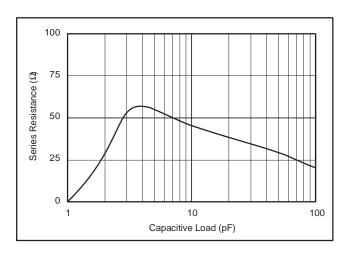


Figure 3. Recommended RS and CL Combinations

Amplifiers configured in unity gain are most susceptible to stability issues. The typical characteristic, Frequency Response vs Capacitive Load, describes the relationship between capacitive load and stability for the OPA300/OPA301 series. In unity gain. OPA300/OPA301 series is capable of driving a few picofarads of capacitive load without compromising stability. Board level parasitic capacitance can often fall into the range of a picofarad or more, and should be minimized through good circuit-board layout practices avoid compromising the stability of OPA300/OPA301. For more information on detecting parasitics during testing, see the Application Note Measuring Board Parasitics in High-Speed Analog Design (SBOA094), available at the TI web site www.ti.com.

#### **DRIVING A 16-BIT ADC**

The OPA300/OPA301 series feature excellent THD+noise, even at frequencies greater than 1MHz, with a 16-bit settling time of 150ns. Figure 4 shows a total single supply solution for high-speed data acquisition. The OPA300/OPA301 directly drives the ADS8401, a 1.25 mega sample per second (MSPS) 16-bit data converter. The OPA300/OPA301 is configured in an inverting gain of 1, with a 5V single supply. Results of the OPA300/OPA301 performance are summarized in Table 1.

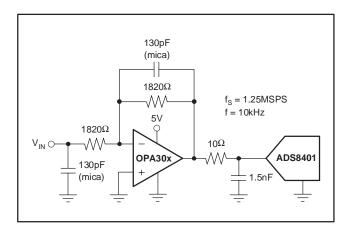


Figure 4. The OPA30x Drives the 16-Bit ADS8401

PARAMETER	RESULTS (f = 10kHz)		
THD	-99.3dB		
SFDR	101.2dB		
THD+N	84.2dB		
SNR	84.3dB		

Table 1. OPA30x Performance Results Driving a 1.25MSPS ADS8401





22-Nov-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
OPA2300AIDGSR	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2300AIDGSRG4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2300AIDGST	ACTIVE	MSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2300AIDGSTG4	ACTIVE	MSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2301AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2301AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2301AIDGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2301AIDGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2301AIDGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2301AIDGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2301AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2301AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA300AID	ACTIVE	SOIC	D	8	100	TBD	CU NIPDAU	Level-3-235C-168 HR
OPA300AIDBVR	ACTIVE	SOT-23	DBV	6	3000	TBD	CU SNPB	Level-2-240C-1 YEAR
OPA300AIDBVT	ACTIVE	SOT-23	DBV	6	250	TBD	CU SNPB	Level-2-240C-1 YEAR
OPA300AIDR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-3-235C-168 HR
OPA301AID	ACTIVE	SOIC	D	8	100	TBD	CU NIPDAU	Level-3-240C-168 HR
OPA301AIDBVR	ACTIVE	SOT-23	DBV	5	3000	TBD	CU NIPDAU	Level-1-235C-UNLIM
OPA301AIDBVT	ACTIVE	SOT-23	DBV	5	250	TBD	CU NIPDAU	Level-1-235C-UNLIM
OPA301AIDR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-3-240C-168 HR

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder



#### PACKAGE OPTION ADDENDUM

22-Nov-2005

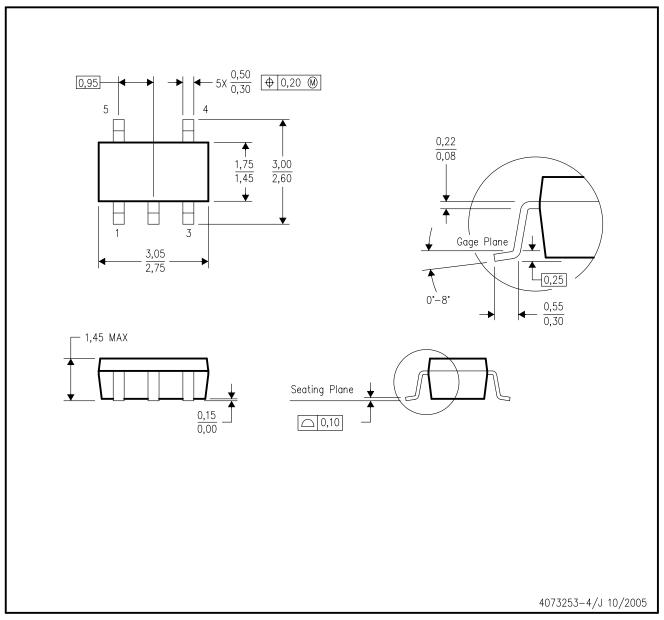
temperature.

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## DBV (R-PDSO-G5)

### PLASTIC SMALL-OUTLINE PACKAGE

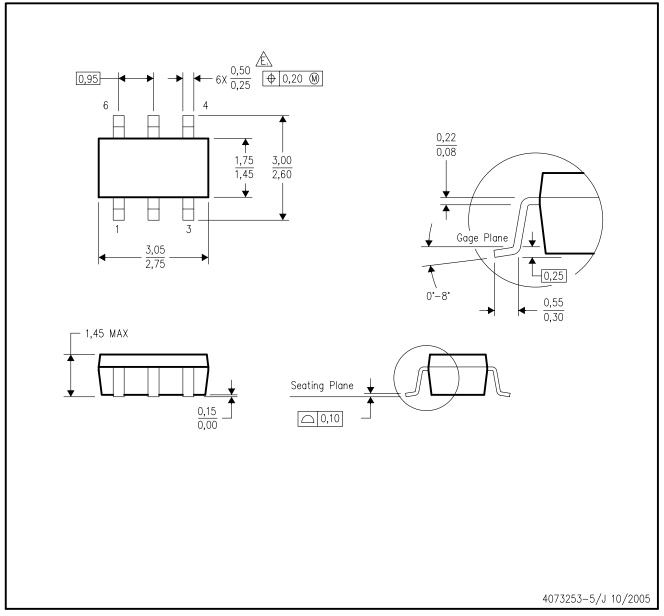


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



## DBV (R-PDSO-G6)

### PLASTIC SMALL-OUTLINE PACKAGE

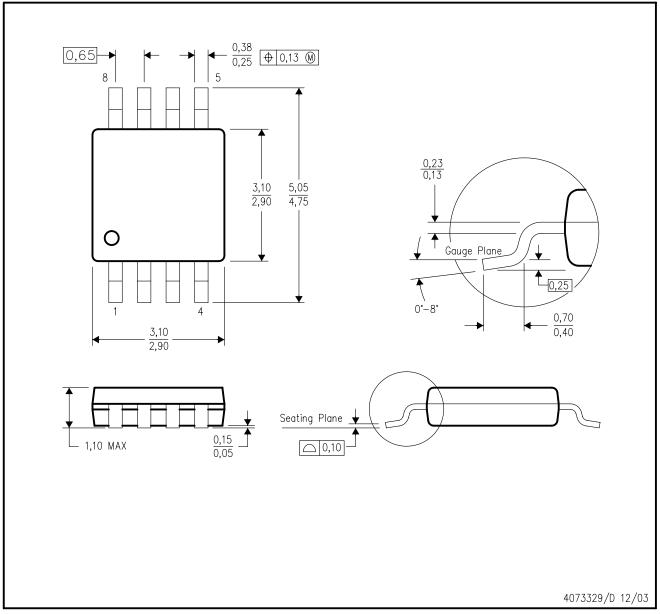


- A. All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



## DGK (S-PDSO-G8)

### PLASTIC SMALL-OUTLINE PACKAGE

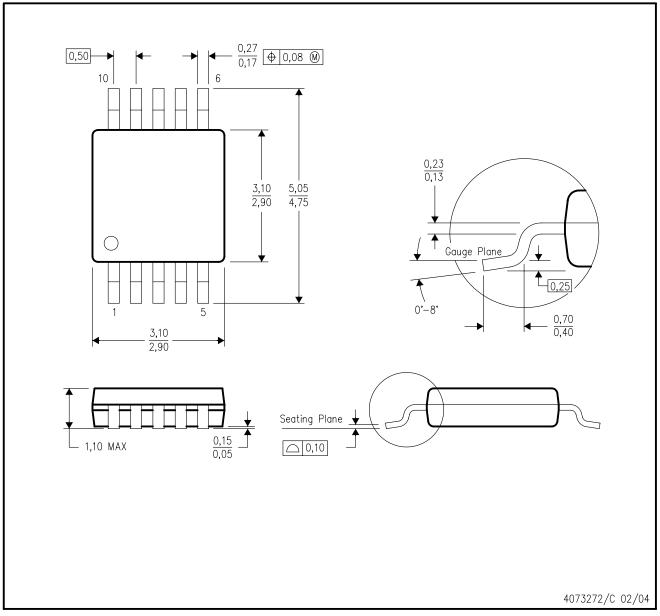


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187 variation AA.



## DGS (S-PDSO-G10)

### PLASTIC SMALL-OUTLINE PACKAGE

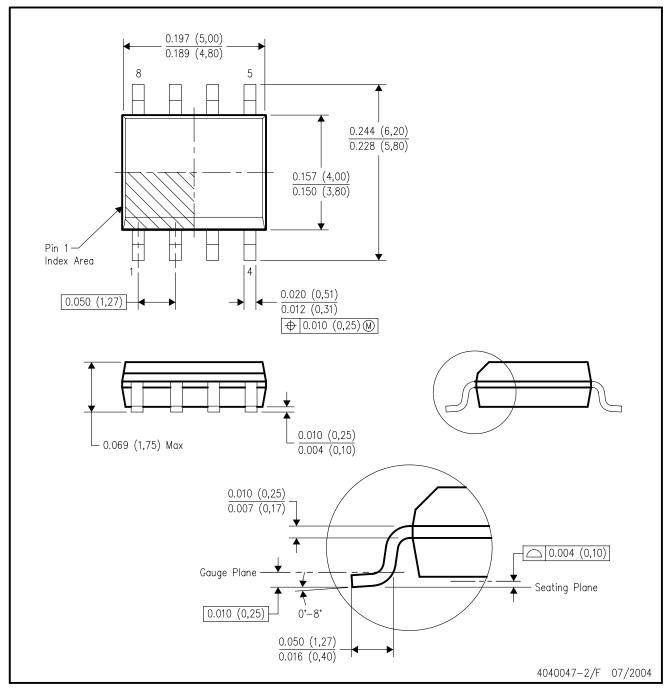


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187 variation BA.



### D (R-PDSO-G8)

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.



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